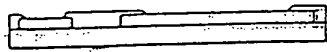
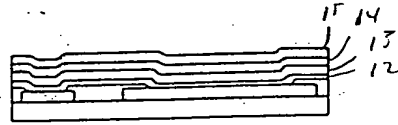


Fig. 1A



Non-Passivated Die

Fig. 1B



Sputter Ti/Cu/Ti/Cu

Fig. 1C

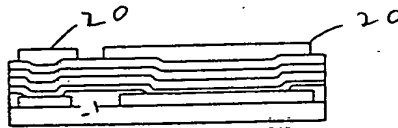
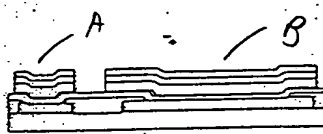


Photo Process, Isolation

Fig. 1D



Isolation Etch, Cu/Ti/Cu

Fig. 1E

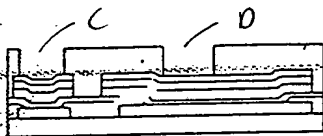
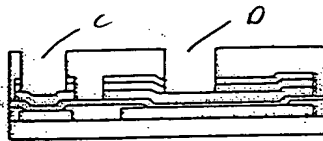


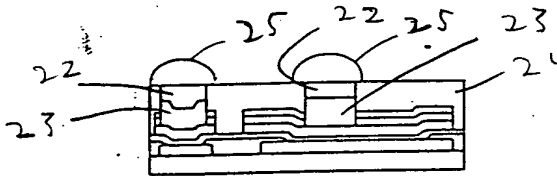
Photo Process, UBM of Bump

Fig. 1F



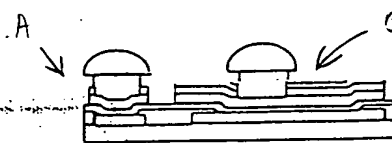
Cu/Ti Etching

Fig. 1G



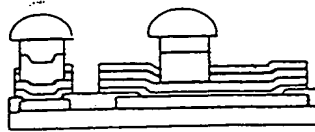
Plating, Cu, Solder

Fig. 1H



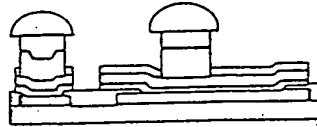
PR Stripping

Fig. 1I



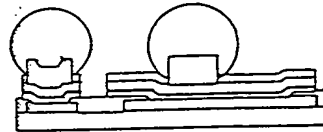
Ti Etching at isolation

Fig. 1J



Cu Etching

Fig. 1K



Solder Reflow

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